IPC ASSOCIATION ELECTRONICS	© Copyright 2005	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information				
upplier	Information													
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi										2024-05-02				
Contact Na	me	Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-E	nv-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorized	Representative*	Title - Representative			I	Phone - Representative*			Email - Representative*					
Product-E	nv-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number		Number	Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Veight*	UOM	Unit Type
		NVMFS5C450NT3G T6-40V N 3.3 mOh		nms SL		2024-05-02	2 MY1		1	07.2528	mg	Each		
	turing Proccess Inform									1			·	·
				STD-020 MSL	Rating		ess Body Tem	•		Temperatu	ire Numb	er of Reflow Cyc	cles	
N	Matte Tin (Sn) - annealed		CU Alloy	1			260	(	2	30	secono	ls   3		
omments														
vel 1 - ma	ximum time at peak tempera	ture during sol	ldering is 10-3	0 seconds										
or more in	nformation regarding materi	al composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Priective 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not independently verified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	13.512	mg	Supplier	Zinc (Zn)	7440-66-6		0.0162	mg
			Supplier	Iron (Fe)	7439-89-6		0.3175	mg
			Supplier	Copper (Cu)	7440-50-8		13.1742	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0041	mg
Die	0.727	mg	Supplier	Silicon (Si)	7440-21-3		0.727	mg
Die Attach Solder	1.4993	mg	Supplier	Silver (Ag)	7440-22-4		0.0375	mg
			A	Lead (Pb)	7439-92-1	7a	1.3869	mg
			Supplier	Tin (Sn)	7440-31-5		0.075	mg
Lead Frame	42.5398	mg	Supplier	Silver (Ag)	7440-22-4		0.0255	mg
			Supplier	Iron (Fe)	7439-89-6		0.0425	mg
			Supplier	Copper (Cu)	7440-50-8		42.459	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0128	mg
Mold Compound-Black	48.7198	mg		Epoxy resin	proprietary data		3.654	mg
			Supplier	Phenolic Resin	Proprietary Data		1.218	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.654	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2436	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		39.9502	mg
Plating	0.2183	mg	Supplier	Tin (Sn)	7440-31-5		0.2183	mg
Wire Bond - Cu	0.0366	mg	Supplier	Copper (Cu)	7440-50-8		0.0366	mg